

**IN THE CLAIMS**

This Listing of Claims will replace all prior versions, and listings of claims in the subject Patent Application:

**Listing of Claims:**

Claims 1-9 (Canceled).

Claim 10 (Currently amended) A method for manufacturing a metal hydride storage canister comprising the steps of:

- a. pre-forming ~~performing~~ a canister body ~~having~~ with an open end;
- b. providing ~~stacking~~ a plurality of wafer baffles, each of ~~which has~~ said wafer baffles having a peripheral wall disposed at a perimeter of a bottom wall thereof and at least one aperture formed at a in said bottom thereof wall and is contained with having metal hydride contained therein;
- c. stacking said plurality of wafer baffles one upon another with said apertures of said plurality of wafer baffles being disposed in aligned relationship, said bottom wall of a respective upper wafer baffle forming a closure for an immediately underlying one of said wafer baffles;

d. ~~[[c.]]~~ passing at least one porous tubing ~~, in term,~~ through ~~the~~ said at least one aperture of each of ~~the~~ said stacked wafer baffles;

e. ~~[[d.]]~~ placing the stacked wafer baffles into ~~the~~ said preformed canister body through ~~the~~ said open end thereof; and

f. ~~[[e.]]~~ heat rolling said open end of said preformed canister to form said storage canister with an making the inner diameter of the preformed canister body approaching an the outer diameter of the said wafer baffles [[,]] and shrinking the open end by heat rolling the preformed canister body and the open end to reducing a diameter of said open end to form an outlet of said storage canister.

Claim 11 (Currently amended) The method according to Claim 10, ~~further comprising where~~ the step of stacking said plurality of wafer baffles one upon another includes the step of placing a lid over an uppermost one of said the stacked wafer baffles to form a closure therefore, before step e., of which the said lid is being formed with at least one opening at a location corresponding to where the at least one disposed in aligned relationship with said apertures of the bottom face of each of the said wafer baffles is formed.